

<b>Form PTO-1449 (modified)</b> List of Patents and Publications For Applicant's Information Disclosure Statement (Use several sheets if necessary)		ATTY. DKT. NO. 5181-62800  APPLICANT: Novak  FILING DATE: June 19, 2000	SERIAL NO. 09/596,863  GROUP: <sup>2817</sup> <del>2836</del>
JUN 11 2001 <b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>			
		Pannala et al., "Contribution of Resonance to Ground Bounce in Lossy Thin Film Planes," © 1998 IEEE, pp. 185-188.	
	B2	Libous, "Characterization of Flip-Chip CMOS ASIC Simultaneous Switching Noise on Multilayer Organic and Ceramic BGA/CGA Packages," © 1998 IEEE, pp. 191-194.	
	B3	Chen et al., "Norton Equivalent Modeling of Microprocessor Core Noise from Measurements," © 1998 IEEE, pp. 195-198.	
	B4	Kim et al., "Rejection of SSN Coupling in Multilayer PCB using a Conductive Layer," <del>© 1998 IEEE, pp. 199-202.</del> <i>REJECTED TO AND IN IEEE</i>	
	B5	Becker et al., "Modeling, Simulation, and Measurement of Mid-Frequency Simultaneous Switching Noise in Computer Systems," IEEE Transactions on Components, Packaging, and Manufacturing Technology-Part B, Vol. 21, No. 2, May 1998, pp. 157-163.	
	B6	Huber et al., "Time-Domain Investigation of Decoupling Capacitors on MCM," May 1999, 2 pgs.	
	B7	Madou et al., "Electrical Characterisation of Capacitors Integrated in Multi-layer Printed Circuit Boards," May 1999, 2 pgs.	
<i>B3</i>	B8	Pham et al., "Decoupling Capacitors Techniques for High Frequency Board Designs," February 1999, pp. 127-135.	
<i>m</i>	B9	Fisher et al., "The Role of Capacitors in High-Speed Systems Design," February 1999, pp. 137-155. <i>High performance design conference</i>	
	B10	Lipa et al., "Flip-Chip Power Distribution," © 1998 IEEE, pp. 39-41.	
	B11	Wu et al., "Accurate Power Supply and Ground Plane Pair Models," © 1998 IEEE, pp. 163-166.	
	B12	Moll et al., "Extraction of Equivalent Circuit Models of Package Power Supply Distribution Systems from Full Wave EM Field Simulations," © 1998 IEEE, pp. 167-170.	
	B13	Fan et al., "Incorporating Vertical Discontinuities in Power-Bus Modeling using a Mixed-Potential Integral Equation and Circuit Extraction Formulation," © 1998 IEEE, pp. 171-174.	
	B14	Zhao et al., "Effects of Power/Ground via Distribution on the Power/Ground Performance of C4/BGA Packages," © 1998 IEEE, pp. 177-180.	
<i>B3</i>	B15	Novak, "Reducing Simultaneous Switching Noise and EMI on Ground/Power Planes by Dissipative Edge Termination," © 1998 IEEE, pp. 181-184.	
<i>m</i>	B16	Herrell et al., "Modeling of Power Distribution Systems in PCs," © 1998 IEEE, pp. 159-162.	
	B17	Chen et al., "Modeling and Simulation of Thin Film Decoupling Capacitors," © 1998 IEEE, pp. 205-208.	
	B18	Diaz-Alvarez et al., "Power Decoupling with Integral Capacitors and Area Array Connections," © 1998 IEEE, pp. 209-212.	
<i>m</i>	B19	Roy et al., "ESR and ESL of Ceramic Capacitor Applied to Decoupling Applications," © 1998 IEEE, pp. 213-216.	

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<b>OTHER ART</b> (Including Author, Title, Date, Pertinent Pages, Etc.)			
		Fang et al., "Modeling of the Electrical Performance of the Power and Ground Supply for a PC Microprocessor on a Card," © 1998 IEEE, pp. 116-119.	
	B21	Shi et al., "An Experimental Procedure for Characterizing Interconnects to the DC Power Bus on a Multilayer Printed Circuit Board," IEEE Transactions on Electromagnetic Compatibility, Vol. 39, No. 4, November 1997, pp. 279-285.	
	B22	Van den Berghe et al., "Study of the Ground Bounce caused by Power Plane Resonances," IEEE Transactions on Electromagnetic Compatibility, Vol. 40, No. 2, May 1998, pp. 111-119.	
	B23	Moran et al., "Application of the Finite-Difference Time-Domain Method and Measurement of Split Ground Plane Structures in Mixed Signal Integrated Circuits and Packages," May 1999, 2 pgs.	
	B24	Lescot et al., "Effect of a Metallic Ground Plane on Advanced CMOS On-Chip Interconnects," May 1999, 2 pgs.	
	B25	Novak, "Probes and Setup for Measuring Power-Plane Impedances with Vector Network Analyzer," February 1999, pp. 201-214.	
	B26	Daniele et al., "Spectral complete model for considering the effects of a finite ground plane on a PCB," 1996, pp. 226-229.	
	B27	Leroux et al., "Modelling of Power Planes for Electrical Simulations," 1996, pp. 664-668.	
	B28	Cai et al., "Numerical Extraction of Partial Inductance of Package Reference (Power/Ground) Planes," © 1995 IEEE, pp. 12-15.	
	B29	Young, "Case Study of Ground Plane Inductance and Implications for Simulation," IEEE Transactions on Components, Packaging, and Manufacturing Technology--Part B, Vol. 18, No. 1, February 1995, pp. 174-178.	
	B30	Peng, "Theory of Wave Guiding by Two-Dimensionally Periodic Structures: Progresses and Challenges," August 1999, 1 pg.	
	B31	Kelly et al., "Band Diagram for a Grounded Periodic Dielectric Substrate with Square Lattice and Finite Height," August 1999, 1 pg.	
	B32	Yang et al., "Fundamental Artificial-Periodic Substrate Effects on Printed Circuit Antennas," August 1999, 1 pg.	
	B33	Tzuang et al., "Guiding and Leaky Characteristics of Microstrip above Perforated Ground Plane," August 1999, 1 pg.	
	B34	Amari et al., "Simple Rules for Truncation of Periodic Structures to Achieve a Prescribed Bandcap Attenuation Level," August 1999, 1pg.	

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MAY 11 2001 <b>U.S. PATENT DOCUMENTS</b>							
EXAM. INITIALS	PAT. NO.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	A1	3,209,284	9/1965	Hast	333	22RX	
	A2	3,678,417	7/1972	Ragan et al.	333	22R	
	A3	4,371,746	2/1983	Pepper, Jr.	178	18	
	A4	4,626,889	12/1986	Yamamoto et al.	333	22RX	
	A5	5,114,912	5/1992	Benz	585	101	
	A6	5,266,036	11/1993	Lichtenwalter et al.	139	65	
	A7	5,523,727	6/1996	Shingyoji	333	22R	
	A8	5,670,917	9/1997	Mazzochette	333	22R	
	A9	5,708,400	1/1998	Morris	333	12	
	A10	5,818,315	10/1998	Moongilan	333	22R	
	A11	6,104,258	8/2000	Novak	333	22R	
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
	A12	Patent Abstracts of Japan, publication no. 05335812, published December 17, 1993.					
	A13	Patent Abstracts of Japan, publication no. 05055813, published March 5, 1993.					
	A14	Patent Abstracts of Japan, publication no. 05145306, published June 11, 1993.					
	A15	Abstract for SU 433 898, published October 30, 1982.					
	A16	Lei et al., "Power Distribution Noise Suppression Using Transmission Line Termination Techniques," © 1996 IEEE, pp. 100-102.					
	A17	O'Sullivan et al., "Developing a Decoupling Methodology with SPICE for Multilayer Printed Circuit Boards," © 1998 IEEE, pp. 652-655.					
	A18	Bandyopadhyay et al., "Importance of Damping and Resonance in Thin-Film Integrated Decoupling Capacitor Design," © 1997 IEEE, pp. 31-34.					
	A19	Fang et al., "Effects of Losses in Power and Ground Planes in the Simulation of Simultaneous Switching Noise," Proceedings of the 3rd Topical Meeting on Electrical Performance of Electronic Packaging, 1994 pp. 110-112.					
	A20	Franz et al., "An Approach to Determine Decoupling Effects of VCC and VCG Structures in Multilayer Technique," Proceedings of the 1994 EMC Symposium, May 1994, pp. 56-59.					
	A21	Ramo et al., <u>Fields and Waves in Communication Electronics</u> , Third Edition, John Wiley & Sons, Inc., 1994, Chapter 9, pp. 464-467.					
	A22	Lee et al., "Modeling and Analysis of Multichip Module Power Supply Planes," IEEE Transactions on Components, Packaging, and Manufacturing Technology--Part B, Vol. 18, No. 4, November 1995, pp. 628-639.					

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